

Abstract

5 A manufacturing method for a semiconductor device using a wire
bonding method using a metal wire. In the wire bonding method, an impact
load applied when a metal ball formed at the tip of the metal wire by electric
discharge is brought into contact with a terminal electrode of a semiconductor
device is smaller than a static load applied after the metal ball is brought into
contact with the terminal electrode. The method makes it possible to prevent
an element or wiring from being damaged while securing the pressure
10 necessary for bonding the metal ball to the terminal electrode even when the
terminal electrode is placed on the element or the wiring.

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